Power MOSFET

–60 V, –14 A, 52 m Ω , Single P–Channel

Features

- Small Footprint (3.3 x 3.3 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- NVTFS5116PLWF Wettable Flanks Product
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parar	Symbol	Value	Unit		
Drain-to-Source Voltage			V_{DSS}	-60	V
Gate-to-Source Voltage	e		V_{GS}	±20	V
Continuous Drain Cur-		$T_{mb} = 25^{\circ}C$	I _D	-14	Α
rent R _{ΨJ-mb} (Notes 1, 2, 3, 4)	Steady	T _{mb} = 100°C		-10	
Power Dissipation	State	T _{mb} = 25°C	P _D	21	W
R _{ΨJ-mb} (Notes 1, 2, 3)		T _{mb} = 100°C		10	
Continuous Drain Cur-		T _A = 25°C	I _D	-6	Α
rent R _{0JA} (Notes 1 & 3, 4)	Steady State	T _A = 100°C		-4	
Power Dissipation		T _A = 25°C	P _D	3.2	W
R _{θJA} (Notes 1, 3)		T _A = 100°C		1.6	
Pulsed Drain Current	Pulsed Drain Current $T_A = 25^{\circ}C$, $t_p = 10 \mu s$			-126	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	–55 to +175	°C
Source Current (Body D	I _S	-17	Α		
Single Pulse Drain-to-Source Avalanche Energy (T _J = 25°C, V _{DD} = 50 V, V _{GS} = 10 V, $I_{L(pk)}$ = 30 A, L = 0.1 mH, R _G = 25 Ω)			E _{AS}	45	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS (Note 1)

Parameter	Symbol	Value	Unit
Junction-to-Mounting Board (top) - Steady State (Note 2 and 3)	$R_{\PsiJ-mb}$	7.2	°C/W
Junction-to-Ambient - Steady State (Note 3)	$R_{\theta JA}$	47	

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Psi (Ψ) is used as required per JESD51–12 for packages in which substantially less than 100% of the heat flows to single case surface.
- 3. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

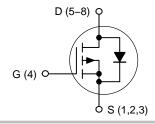


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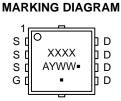
V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX	
-60 V	52 m Ω @ $-$ 10 V	–14 A	
	72 mΩ @ –4.5 V	-14 A	

P-Channel MOSFET





WDFN8 (μ8FL) CASE 511AB



XXXX = Specific Device Code
A = Assembly Location

Y = Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

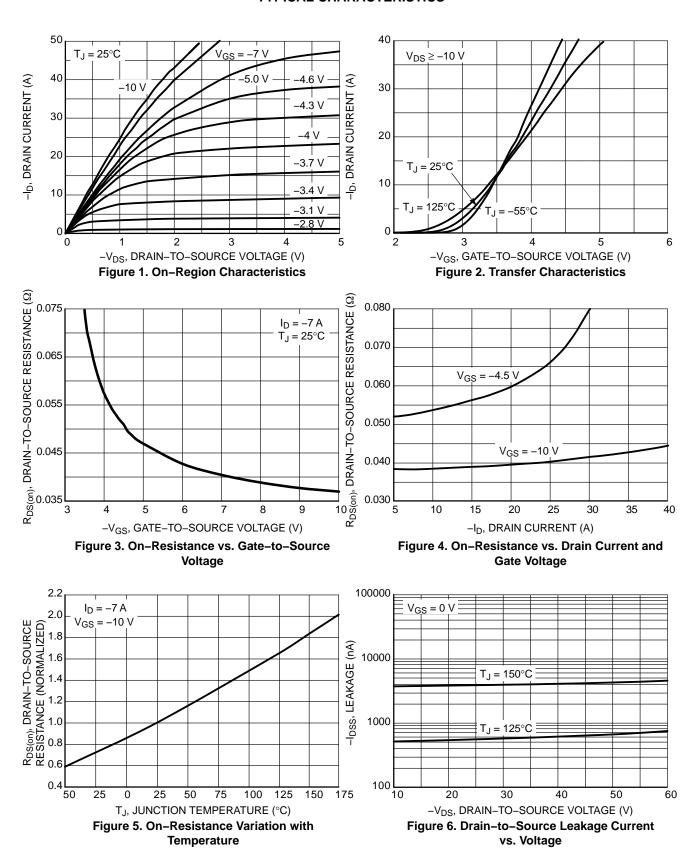
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

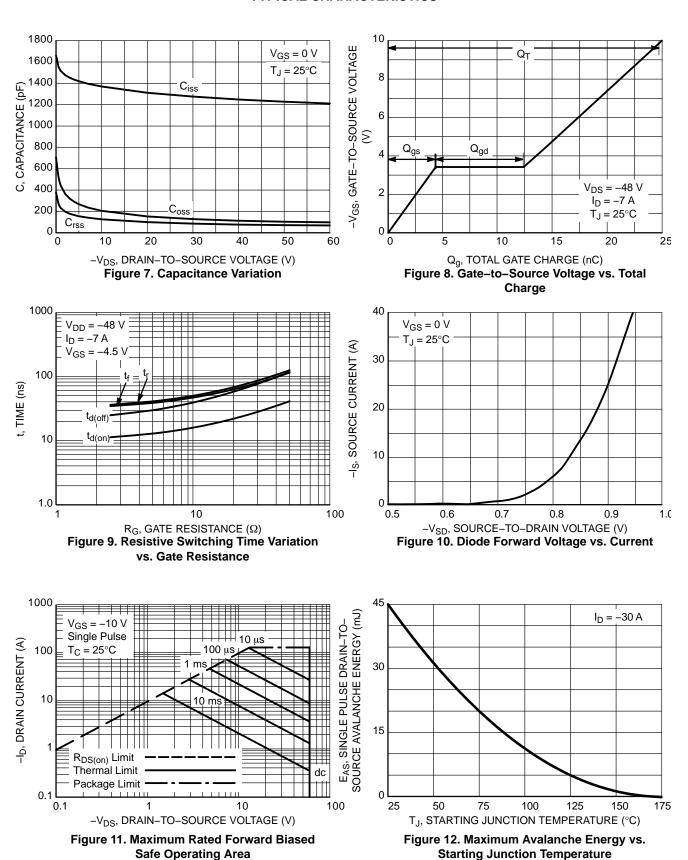
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS					•	•		
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-60			V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 60 V	T _J = 25°C			-1.0	μΑ	
			T _J = 125°C			-10		
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{G}$	_S = ±20 V			±100	nA	
ON CHARACTERISTICS (Note 5)								
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D}$	= -250 μA	-1		-3	V	
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = -10 \text{ V},$	I _D = -7 A		37	52	mΩ	
		$V_{GS} = -4.5 \text{ V}_{S}$	I _D = -7 A		51	72		
Forward Transconductance	9FS	V _{DS} = 15 V,	I _D = -5 A		11		S	
CHARGES AND CAPACITANCES								
Input Capacitance	C _{iss}	V _{GS} = 0 V, f =	1.0 MHz,		1258		pF	
Output Capacitance	C _{oss}	V _{DS} = -	25 V		127		1	
Reverse Transfer Capacitance	C _{rss}				84			
Total Gate Charge	$Q_{G(TOT)}$				14		nC	
Threshold Gate Charge	Q _{G(TH)}	VGS = -4.5 V. V	'ns = -48 V.		1		nC	
Gate-to-Source Charge	Q _{GS}	$V_{GS} = -4.5 \text{ V}, V_{DS} = -48 \text{ V},$ $I_{D} = -7 \text{ A}$			4			
Gate-to-Drain Charge	Q_{GD}				8			
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -10 \text{ V}, V_{DS} = -48 \text{ V},$ $I_{D} = -7 \text{ A}$			25		nC	
SWITCHING CHARACTERISTICS (No	te 6)				•	•		
Turn-On Delay Time	t _{d(on)}				14		ns	
Rise Time	t _r	$V_{GS} = -4.5 \text{ V. V}$	ne = -48 V.		68		1	
Turn-Off Delay Time	t _{d(off)}	$V_{GS} = -4.5 \text{ V, V}$ $I_{D} = -7$	7 A		24			
Fall Time	t _f				36			
DRAIN-SOURCE DIODE CHARACTER	ISTICS				•	•		
Forward Diode Voltage	V _{SD}	$V_{GS} = 0 V$	$T_J = 25^{\circ}C$		-0.79	-1.20	V	
		$I_S = -7 A$	T _J = 125°C		-0.64		1	
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } dI_S/dt = 100 \text{ A/}\mu\text{s,}$ $I_S = -7 \text{ A}$			21		ns	
Charge Time	ta				16		1	
Discharge Time	t _b				5		1	
Reverse Recovery Charge	Q _{RR}				24		nC	

^{5.} Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

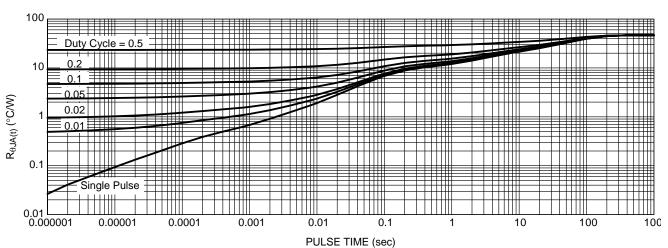


Figure 13. Thermal Response

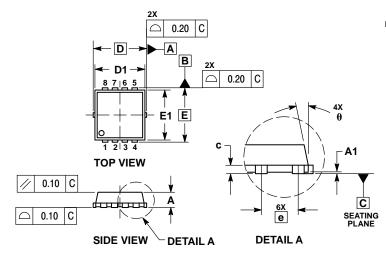
DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]	
NVTFS5116PLTAG	5116	WDFN8 (Pb-Free)	1500 / Tape & Reel	
NVTFS5116PLWFTAG	16LW	WDFN8 (Pb-Free)	1500 / Tape & Reel	
NVTFS5116PLTWG	5116	WDFN8 (Pb-Free)	5000 / Tape & Reel	
NVTFS5116PLWFTWG	16LW	WDFN8 (Pb-Free)	5000 / Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

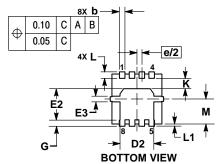
WDFN8 3.3x3.3, 0.65P CASE 511AB ISSUE D

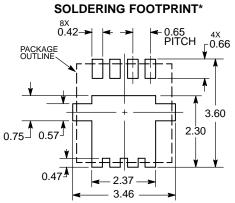


NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.75	0.80	0.028	0.030	0.031	
A1	0.00		0.05	0.000		0.002	
b	0.23	0.30	0.40	0.009	0.012	0.016	
С	0.15	0.20	0.25	0.006	0.008	0.010	
D		3.30 BSC			0.130 BSC		
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
E		3.30 BSC		0.130 BSC			
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	0.23	0.30	0.40	0.009	0.012	0.016	
е	0.65 BSC		0.026 BSC				
G	0.30	0.41	0.51	0.012	0.016	0.020	
K	0.65	0.80	0.95	0.026	0.032	0.037	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
M	1.40	1.50	1.60	0.055	0.059	0.063	
θ	0 °		12 °	0 °		12 °	





DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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